APPLICATION DATA SHEET

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Application Information

Title : METHOD AND SYSTEM FOR ELECTRICALLY

COUPLING A CHIP TO CHIP PACKAGE

Total Drawing Sheets : 3
Formal Drawings : YES
Application Type : Utility
Attorney Docket Number : 501039.03

Assigned : Yes (Large Entity)

Representative Information

Representative Customer No. : 27,076

Continuity Information

This application is a : divisional of Application One : 09/978,983 Filing Date : October 15, 2001

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